



CDTech(H.K.)Electronics Limited

Product Specification

Model Name	S024HQ42NN-DC05
Description	TFT LCD Module 2.4" QVGA 240(RGB)x320 Dots
Date	2019/6/18
Version	1.0

Approved by/Date	Check by/Date	Prepared by/Date
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Customer Approval	
Date	



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Table of Contents

1. Record of Revision.....	3
2. General Specifications.....	4
3. Input/Output Terminals.....	5
4. Absolute Maximum Rating.....	6
5. Timing characteristics.....	6
6. Interface Timing.....	9
7 Optical Characteristics.....	19
8 Environmental / Reliability Tests.....	23
9 Mechanical Drawing.....	24
10 Packing.....	25
11 TFT-LCD Module Inspection Criteria.....	26
12 Precautions for Use of LCD modules.....	31

2. General Specifications

Feature		Spec
Characteristics	Size	2.4 inch
	Resolution	240(horizontal)*320(Vertical)
	Interface	MCU-18/16/9/8 Bit RGB-18/16/6 Bit SPI 3-Line&4-Line
	Connect type	Connector
	Display Colors	65K/262K
	Technology type	a-Si
	Pixel pitch (mm)	0.153*0.153
	Pixel Configuration	R.G.B.-Stripe
	Display Mode	Normally Black
	Driver IC	ILI9340X
	CTP Driver IC	GT911
	Viewing Direction	Full view
Mechanical	LCM (W x H x D) (mm)	42.72*60.26*4.00
	Active Area(mm)	36.72*48.96
	With /Without TSP	With CTP
	Weight (g)	TBD
	LED Numbers	4 LEDs

Note 1: Requirements on Environmental Protection: RoHs

Note 2: LCM weight tolerance: +/- 5%

3. Input/Output Terminals

LCD PIN-MAP

PIN NO.	PIN NAME	DESCRIPTION																																																				
1	VCI	Power supply.																																																				
2	IOVCC	Digital power supply.																																																				
3	IM0	<table border="1"> <tr> <td>1</td> <td>0</td> <td>0</td> <td>0</td> <td>80 MCU 16-bit bus interface II</td> <td>D[8:1]</td> <td>D[17:10], D[8:1]</td> </tr> <tr> <td>4</td> <td>IM3</td> <td>1</td> <td>0</td> <td>0</td> <td>1</td> <td>80 MCU 8-bit bus interface II</td> <td>D[17:10]</td> <td>D[17:10]</td> </tr> <tr> <td>5</td> <td>IM2</td> <td>1</td> <td>0</td> <td>1</td> <td>0</td> <td>80 MCU 18-bit bus interface II</td> <td>D[8:1]</td> <td>D[17:0]</td> </tr> <tr> <td>6</td> <td>IM1</td> <td>1</td> <td>0</td> <td>1</td> <td>1</td> <td>80 MCU 9-bit bus interface II</td> <td>D[17:10]</td> <td>D[17:9]</td> </tr> <tr> <td></td> <td></td> <td>1</td> <td>1</td> <td>0</td> <td>1</td> <td>3-wire 9-bit data serial interface II</td> <td colspan="2">SDI: In SDO: Out</td> </tr> <tr> <td></td> <td></td> <td>1</td> <td>1</td> <td>1</td> <td>0</td> <td>4-wire 8-bit data serial interface II</td> <td colspan="2">SDI: In SDO: Out</td> </tr> </table>	1	0	0	0	80 MCU 16-bit bus interface II	D[8:1]	D[17:10], D[8:1]	4	IM3	1	0	0	1	80 MCU 8-bit bus interface II	D[17:10]	D[17:10]	5	IM2	1	0	1	0	80 MCU 18-bit bus interface II	D[8:1]	D[17:0]	6	IM1	1	0	1	1	80 MCU 9-bit bus interface II	D[17:10]	D[17:9]			1	1	0	1	3-wire 9-bit data serial interface II	SDI: In SDO: Out				1	1	1	0	4-wire 8-bit data serial interface II	SDI: In SDO: Out	
1	0	0	0	80 MCU 16-bit bus interface II	D[8:1]	D[17:10], D[8:1]																																																
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		1	1	0	1	3-wire 9-bit data serial interface II	SDI: In SDO: Out																																															
		1	1	1	0	4-wire 8-bit data serial interface II	SDI: In SDO: Out																																															
7	RESET	Reset signal input terminal																																																				
8	VSYNC	Vertical Sync signal																																																				
9	HSYNC	Horizontal Sync signal																																																				
10	DOTCLK	Dot clock signal.																																																				
11	ENABLE	Data Enable																																																				
12~29	DB17~DB0	DATA BUS.																																																				
30	SDO	Serial output data																																																				
31	SDI	Serial Input Data.																																																				
32	RD	Read signal																																																				
33	WR/(D/CX)	8080-I system :Write signal Serial interface: Data or command select.																																																				
34	RS/(SCL)	8081-I system :Data or command select. Serial interface:Serial clock signal.																																																				
35	CS	Chip select																																																				
36	GND	System Ground																																																				
37	LEDA	LED Anode.																																																				
38	LEDK	LED Cathode.																																																				
39	LEDK	LED Cathode.																																																				
40	NC	No connection																																																				
41	NC	No connection																																																				
42	NC	No connection																																																				
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45	NC	No connection																																																				

CTP PIN-MAP

Pin	Signal	Description
1	GND	Ground
2	SCL (2.8V)	I2C clock input
3	SDA (2.8V)	I2C data input and output
4	INT (2.8V)	Interrupt request to the host
5	RESET	Reset Pin for CTP
6	VCC	Power supply for CTP

4. Absolute Maximum Rating

Driving TFT LCD Panel

Item	Symbol	MIN	MAX	Unit	Remark
Supply Voltage	V _{CC}	2.5	4.8	V	
Input Voltage	IOVCC	1.65	3.3	V	
Operating Temperature	T _{OPR}	-20	70	°C	
Storage Temperature	T _{STG}	-30	80	°C	

5. Timing characteristics

5.1 ELECTRICAL CHARACTERISTICS

Item	Symbol	MIN	TYP	MAX	Unit	Remark
Analog Supply Voltage	V _{CC}	2.5	2.8	3.3	V	
Logic Signal Input /Output Voltage	IOVCC	1.65	1.8	3.3	V	
Input Signal Voltage	Low Level	V _{IL}	V _{SS}	-	0.3x IOVCC	V
	High Level	V _{IH}	0.7x IOVCC	-	IOVCC	V
TFT Common Electrode	V _{COMH}	2.5	-	5	V	
TFT Gate ON Voltage	V _{GH}	10	-	16	V	
TFT Gate ON Voltage	V _{GL}	-10	-	-5	V	

5.2 CTP Electrical Characteristics

FPC Design	Item	Description	Remark
COF	IC solution on TP Model	GT911	
	Touch Count Max	5 point	
	Display Resolution	240*320	
	Interface Type	I2C	
	I2C Slave Address	-	
	Origin of Coordinate	Top left corner	

5.3 LED Driving Conditions

Item	Symbol	MIN	TYP	MAX	Unit	Remark
Forward Current	I_F	-	20	-	mA	
Forward Voltage	V_F	9.0	12.0	10.2	V	
LED Lifetime		-	30000	-	Hrs	

Note 1: Each LED: $I_F = 20 \text{ mA}$, $V_F = 3.2 \pm 0.2 \text{ V}$.

Note 2: Optical performance should be evaluated at $T_a = 25^\circ \text{C}$ only.

Note 3: If LED is driven by high current, high ambient temperature & humidity condition. The life Time of LED will be reduced. Operating life means brightness goes down to 50% initial brightness. Typical operating life time is estimated data.

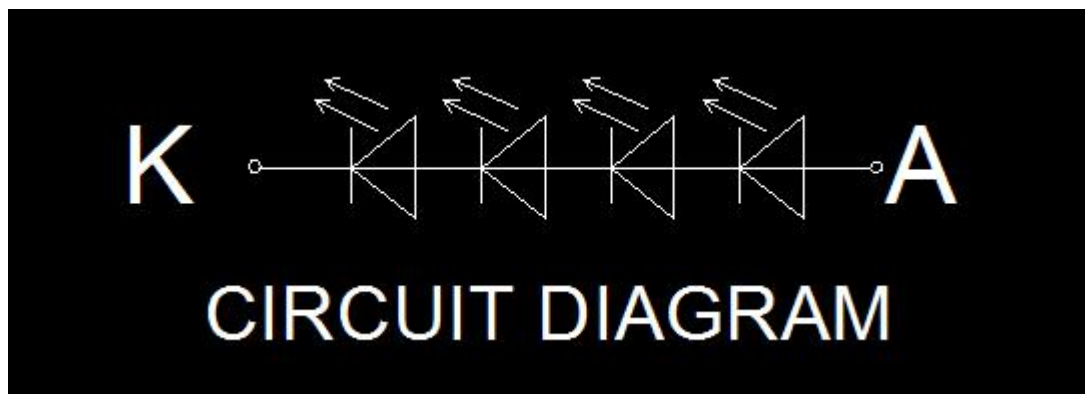
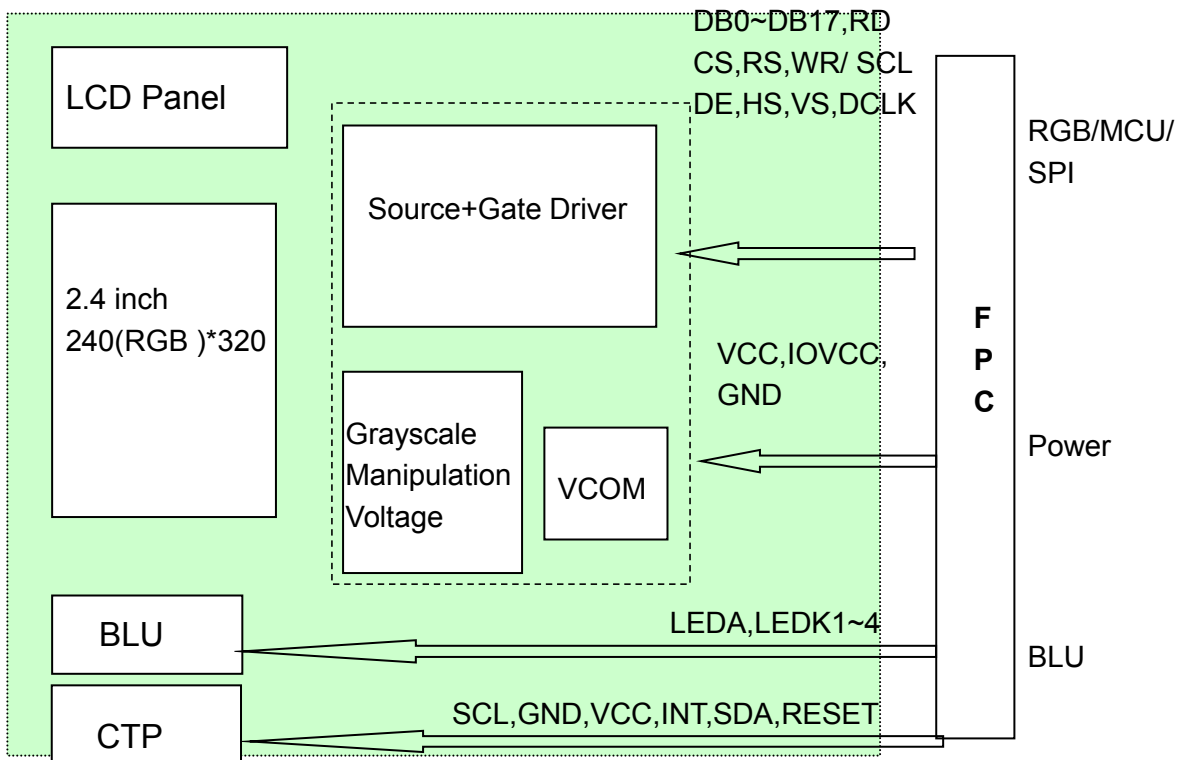


Figure: LED connection of backlight(Constant Current)

5.4 Block Diagram



6. Interface Timing

6.1 DC Electrical Characteristics

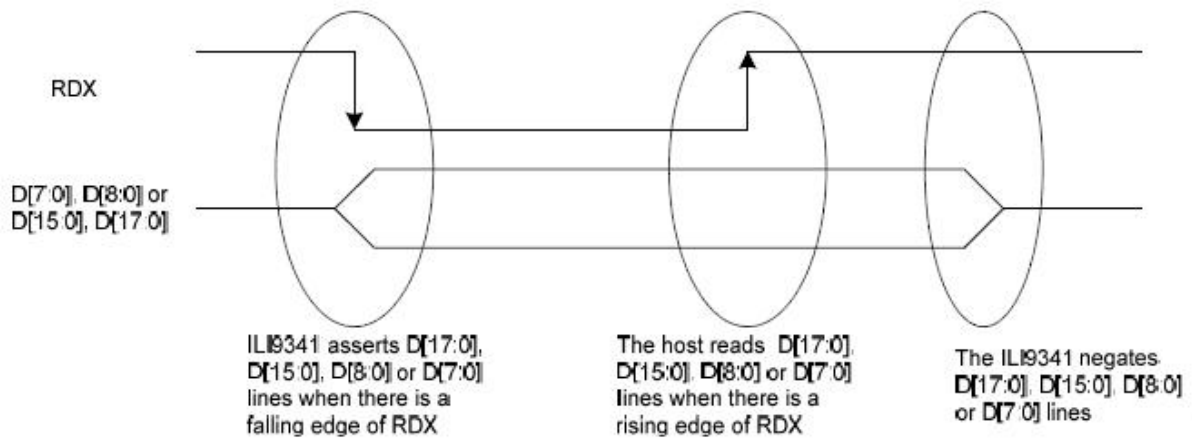
Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
VDDIO	Power supply pin of IO pins	Recommend Operating Voltage Possible Operating Voltage	1.4	-	3.3	V
VCI	Booster Reference Supply Voltage Range	Recommend Operating Voltage Possible Operating Voltage	2.5 or VDDIO whichever is higher	-	3.3	V
VGH	Gate driver High Output Voltage Booster efficiency	No panel loading; 4x or 5x booster; ITO for CYP, CYN, VCIX2, VCI and VCHS = 10 Ohm	88	90	-	%
		No panel loading; 6x booster; ITO for CYP, CYN, VCIX2, VCI and VCHS = 10 Ohm	82	84	-	%
VCIX2	VCIX2 primary booster efficiency	No panel loading, ITO for CYP, CYN, VCIX2, VCI and VCHS = 10 Ohm	83	85	-	%
VGH	Gate driver High Output Voltage		9	-	18	V
VGL	Gate driver Low Output Voltage		-15	-	-6	V
VcomH	Vcom High Output Voltage		$V_{CI} + 0.5$	-	5	V
VcomL	Vcom Low Output Voltage		$-V_{CIM} + 0.5$	-	-1	V
VLCD63	Max. Source Voltage		-	-	6	V
Δ VLCD63	Source voltage variation		-2		2	%
V _{OH1}	Logic High Output Voltage	I _{out} = -100 μ A	0.9*VDDIO	-	VDDIO	V
V _{OL1}	Logic Low Output Voltage	I _{out} = 100 μ A	0	-	0.1*VDDIO	V
V _{IH1}	Logic High Input voltage		0.8*VDDIO	-	VDDIO	V
V _{IL1}	Logic Low Input voltage		0	-	0.2*VDDIO	V
I _{OH}	Logic High Output Current Source	V _{out} = V _{DDIO} - 0.4V	50	-	-	μ A
I _{OL}	Logic Low Output Current Drain	V _{out} = 0.4V	-	-	-50	μ A
I _{oz}	Logic Output Tri-state Current Drain Source		-1	-	1	μ A
I _L /I _{IH}	Logic Input Current		-1	-	1	μ A

C _{IN}	Logic Pins Input Capacitance		-	5	7.5	pF	
R _{SON}	Source drivers output resistance		-	1	-	k Ω	
R _{GON}	Gate drivers output resistance		-	5	-	k Ω	
R _{CON}	Vcom output resistance		-	200	-	Ω	
I _{dp} (262k)	Display current for 262k	V _{ddio} = 1.8V, V _{ci} = 2.8V. 5x/-5x booster ratio. Full color current consumption, without panel loading	I _{vdd}	-	150	300	μ A
			I _{vci}	-	2.5	8	mA
I _{dp} (8 color)	Display current for 8 color mode	Current consumption for 8 color partial display, without panel loading	I _{vdd}	-	120	300	μ A
			I _{vci}	-	1	5	mA
I _{slp}	Sleep mode current	Oscillator off, no source/gate output, Ram read write halt. Send command R10-0001 (sleep mode)	I _{vdd}	-	0.5	1	μ A
			I _{vci}	-	10	75	μ A

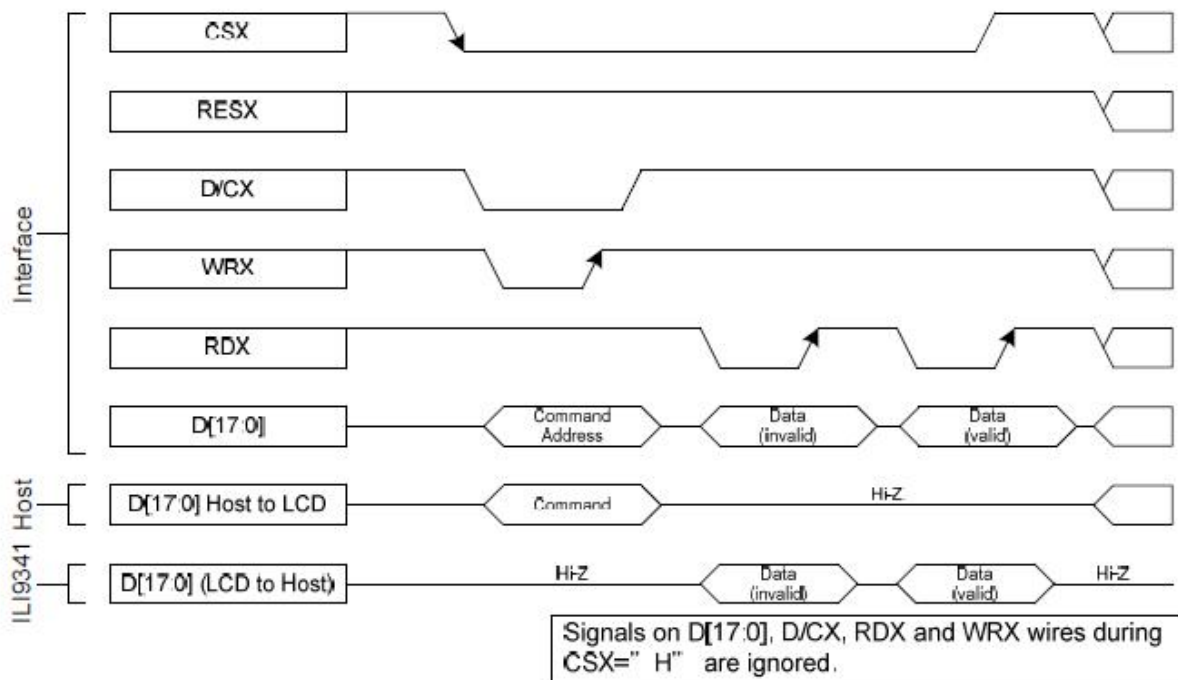
Remark: I_{vdd} = I_{vddio}

Note: The DC characteristic is base on only N-buffer or only P-buffer mode. (Refer to R3Fh command)

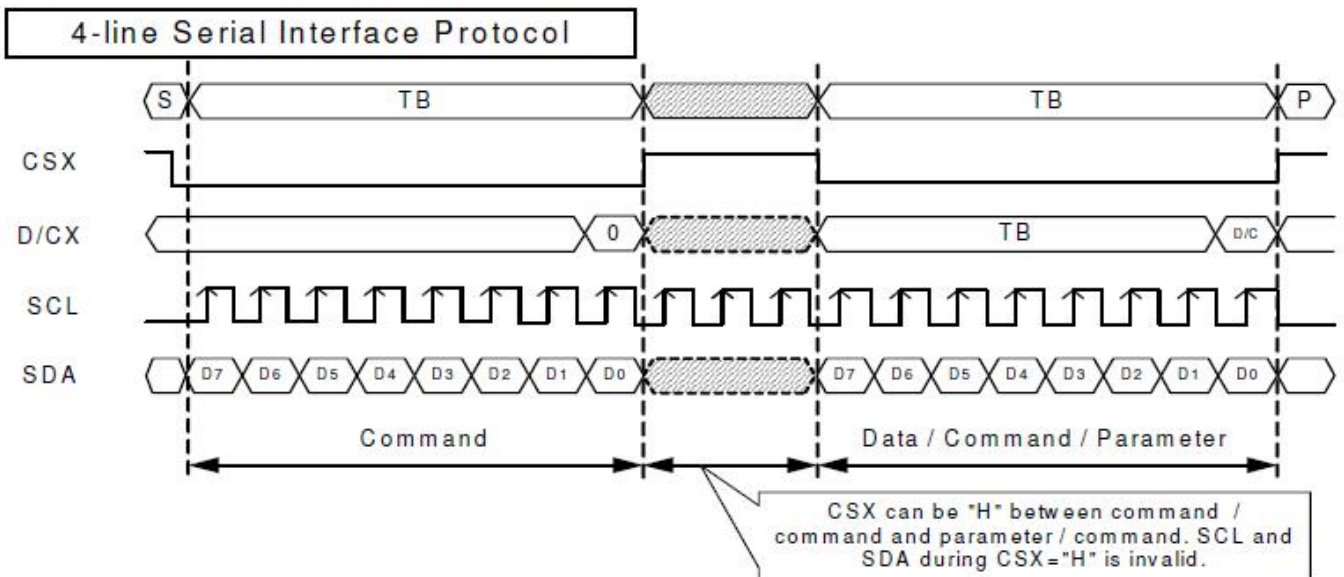
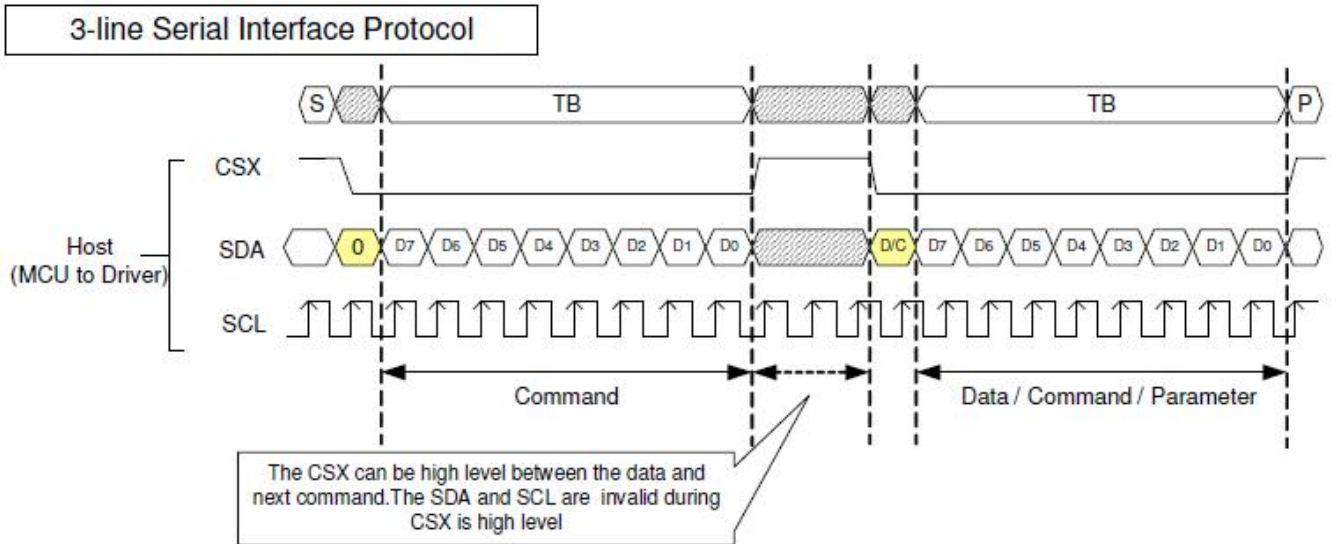
6.2 Timing

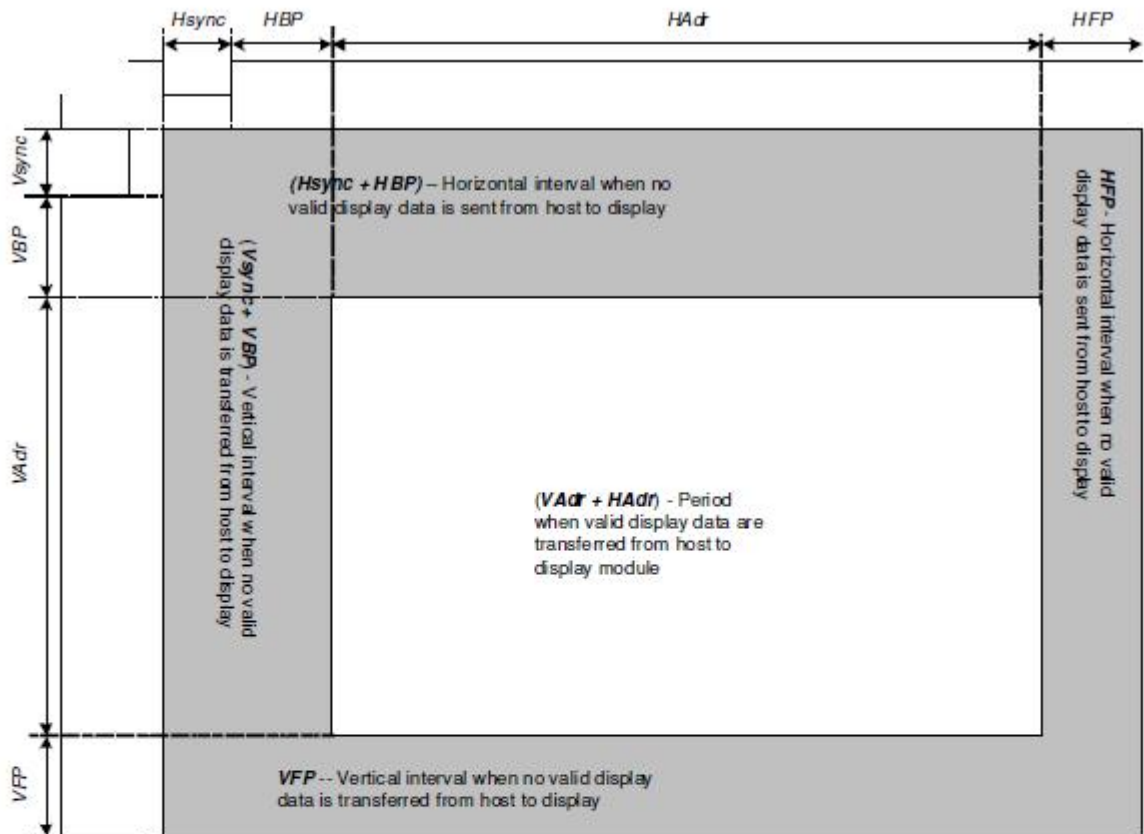


Note: RDX is an unsynchronized signal (It can be stopped).



Host processor drives the CSX pin to low and starts by setting the D/CX bit on SDA. The bit is read by ILI9341 on the first rising edge of SCL signal. On the next falling edge of SCL, the MSB data bit (D7) is set on SDA by the host. On the next falling edge of SCL, the next bit (D6) is set on SDA. If the optional D/CX signal is used, a byte is eight read cycle width. The 3/4-line serial interface writes sequence described in the figure as below.

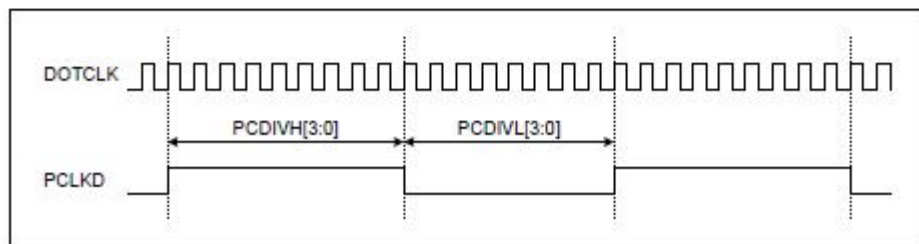
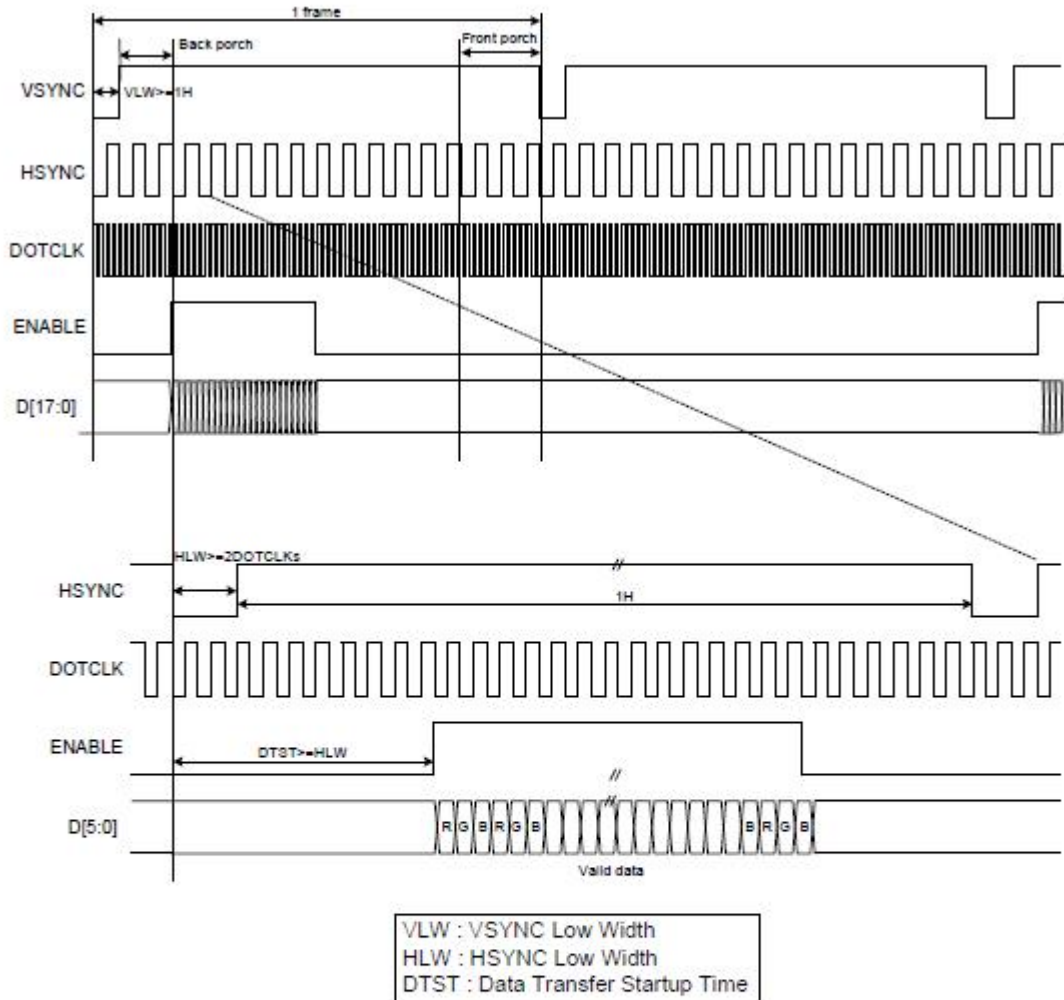




Parameters	Symbols	Condition	Min.	Typ.	Max.	Units
Horizontal Synchronization	Hsync		2	10	16	DOTCLK
Horizontal Back Porch	HBP		2	20	24	DOTCLK
Horizontal Address	HAdr		-	240	-	DOTCLK
Horizontal Front Porch	HFP		2	10	16	DOTCLK
Vertical Synchronization	Vsync		1	2	4	Line
Vertical Back Porch	VBP		1	2	-	Line
Vertical Address	VAdr		-	320	-	Line
Vertical Front Porch	VFP		3	4	-	Line

1.2.2. RGB interface timing

The timing chart of 18-/16-bit RGB interface mode is shown as below.

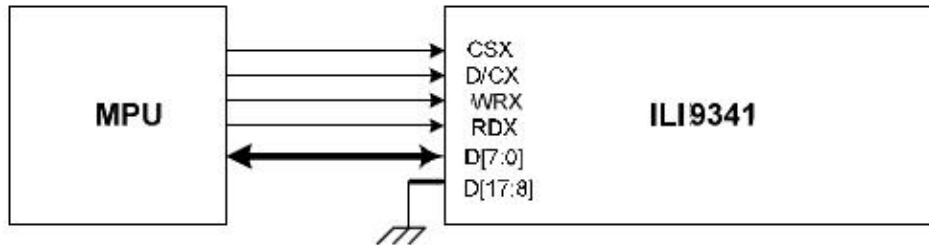


Note 1: The DE signal is not needed when RGB interface SYNC mode is selected.

Note 2: VSPL='0', HSPL='0', DPL='0' and EPL='0' of "Interface Mode Control (B0h)" command.

7.6.3. 8-bit Parallel MCU Interface

The 8080-1 system 8-bit parallel bus interface of ILI9341 can be used by setting external pin as IM [3:0] to "0000". The following shown figure is the example of interface with 8080-1 MCU system interface.



Different display data formats are available for two color depths supported by listed below.

- 65K-Colors, RGB 5, 6, 5 -bits input data.
- 262K-Colors, RGB 6, 6, 6 -bits input data.

65K color: 16-bit/pixel (RGB 5-6-5 bits input)

One pixel (3 sub-pixels) display data is sent by 2 byte transfers when DBI [2:0] bits of 3Ah register are set to "101".

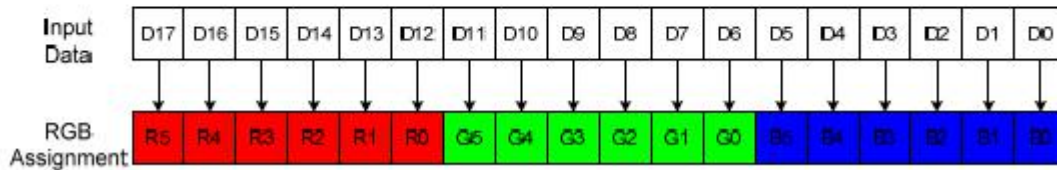
Count	0	1	2	3	4	...	477	478	479	480
D/CX	0	1	1	1	1	...	1	1	1	1
D7	C7	0R4	0G2	1R4	1G2	...	238R4	238G2	239R4	239G2
D6	C6	0R3	0G1	1R3	1G1	...	238R3	238G1	239R3	239G1
D5	C5	0R2	0G0	1R2	1G0	...	238R2	238G0	239R2	239G0
D4	C4	0R1	0B4	1R1	1B4	...	238R1	238B4	239R1	239B4
D3	C3	0R0	0B3	1R0	1B3	...	238R0	238B3	239R0	239B3
D2	C2	0G5	0R2	1G5	1R2	...	238G5	238R2	239G5	239R2
D1	C1	0G4	0B1	1G4	1B1	...	238G4	238B1	239G4	239B1
D0	C0	0G3	0B0	1G3	1B0	...	238G3	238B0	239G3	239B0

65K color: 16-bit/pixel (RGB 5-6-5 bits input)

One pixel (3 sub-pixels) display data is sent by 1 transfer when DBI [2:0] bits of 3Ah register are set to "101".

Count	0	1	2	3	...	238	239	240
D/CX	0	1	1	1	...	1	1	1
D15		0R4	1R4	2R4	...	237R4	238R4	239R4
D14		0R3	1R3	2R3	...	237R3	238R3	239R3
D13		0R2	1R2	2R2	...	237R2	238R2	239R2
D12		0R1	1R1	2R1	...	237R1	238R1	239R1
D11		0R0	1R0	2R0	...	237R0	238R0	239R0
D10		0G5	1G5	2G5	...	237G5	238G5	239G5
D9		0G4	1G4	2G4	...	237G4	238G4	239G4
D8		0G3	1G3	2G3	...	237G3	238G3	239G3
D7	C7	0G2	1G2	2G2	...	237G2	238G2	239G2
D6	C6	0G1	1G1	2G1	...	237G1	238G1	239G1
D5	C5	0G0	1G0	2G0	...	237G0	238G0	239G0
D4	C4	0B4	1B4	2B4	...	237B4	238B4	239B4
D3	C3	0B3	1B3	2B3	...	237B3	238B3	239B3
D2	C2	0B2	1B2	2B2	...	237B2	238B2	239B2
D1	C1	0B1	1B1	2B1	...	237B1	238B1	239B1
D0	C0	0B0	1B0	2B0	...	237B0	238B0	239B0

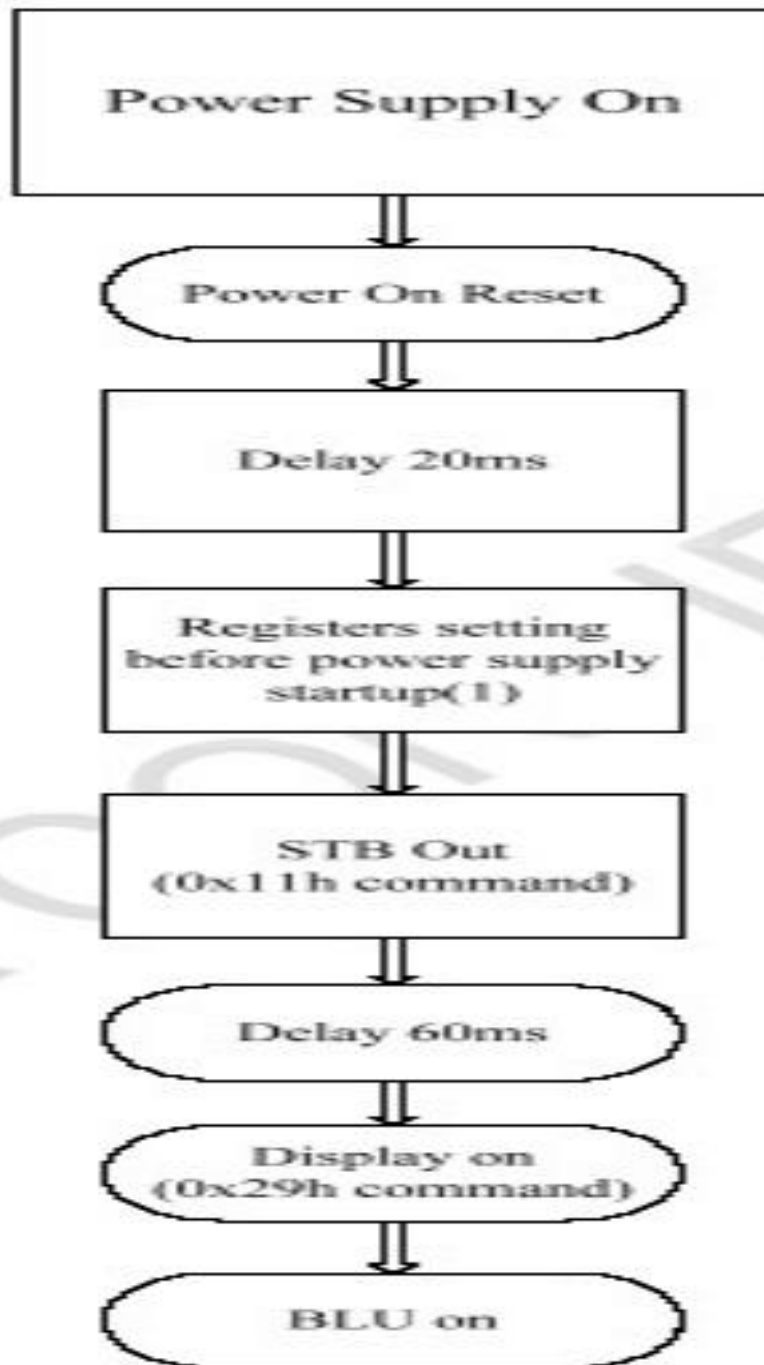
The 18-bit RGB interface is selected by setting the DPI [2:0] bits to "110". When RCM [1:0] are set to "10" and DE mode is selected, the display operation is synchronized with VSYNC, HSYNC and DOTCLK signals. The display data are transferred to the internal GRAM in synchronization with the display operation via 18-bit RGB data bus (D [17:0]) according to the data enable signal (DE) when RCM [1:0] are set to "10". The RGB interface SYNC mode is selected by setting the RCM [1:0] to "11", the valid display data is inputted in pixel unit via D [17:0] according to the VFP/VBP and HFP/HBP settings. Registers can be set by the SPI system interface.



The 16-bit RGB interface is selected by setting the DPI [2:0] bits to "101". When RCM [1:0] are set to "10" and DE mode is selected, the display operation is synchronized with VSYNC, HSYNC and DOTCLK signals. The display data is transferred to the internal GRAM in synchronization with the display operation via 16-bit RGB data bus (D [17:13] & D [11:1]) according to the data enable signal (DE). The RGB interface SYNC mode is selected by setting the RCM [1:0] to "11", the valid display data is inputted in pixel unit via D [17:13] and D [11:1] according to the VFP/VBP and HFP/HBP settings. The unused D12 and D0 pins must be connected to GND for ensure normally operation. Registers can be set by the SPI system interface.



6.3 Power ON/OFF Sequence



6.4 Capacitive touch panel Specification

I2C

The I2C is always configured in the Slave mode. The data transfer format is shown in [Figure 2-4](#).

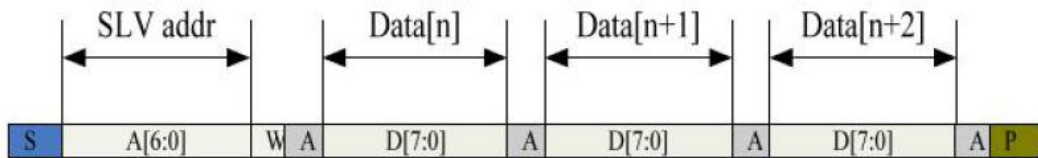
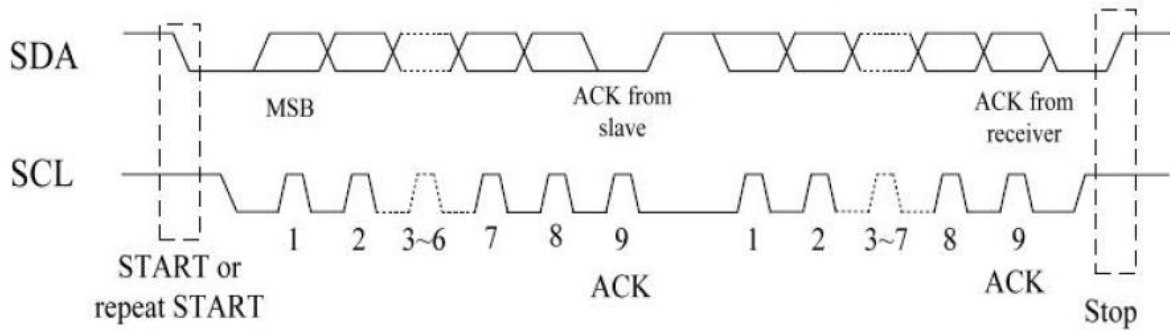


Figure 2-5 I2C master write, slave read

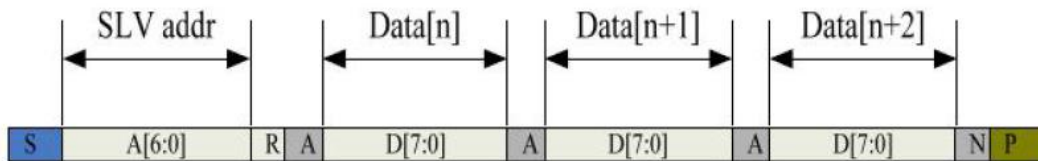


Figure 2-6 I2C master read, slave write

Table 2-1 lists the meanings of the mnemonics used in the above figures.

Table 2-1 Mnemonics Description

Mnemonics	Description
S	I2C Start or I2C Restart
A[6:0]	Slave address A[6:4]: 3'b011 A[3:0]: data bits are identical to those of I2CCON[7:4] register.
W	1'b0: Write
R	1'b1: Read
A(N)	ACK(NACK)
P	STOP: the indication of the end of a packet (if this bit is missing, S will indicate the end of the current packet and the beginning of the next packet)

I2C Interface Timing Characteristics is shown in Table 2-2.

Table 2-2 I2C Timing Characteristics

Parameter	Unit	Min	Max
SCL frequency	KHz	0	400
Bus free time between a STOP and START condition	us	4.7	\
Hold time (repeated) START condition	us	4.0	\
Data setup time	ns	250	\
Setup time for a repeated START condition	us	4.7	\
Setup Time for STOP condition	us	4.0	\

7. Optical Characteristics

Items		Symbol	Condition	Min.	Typ.	Max.	Unit	Remark	Note
Response time		Tr+Tf	-	-	35	45	ms	FIG.1	Note4
Contrast Ratio		CR		300	350	-	-	FIG.2	Note1
Surface luminance		LV	$\theta = 0^\circ$	-	250	-	cd/m2	FIG.2	Note2
Luminance uniformity		Yu	$\theta = 0^\circ$	80	-	-	%	FIG.2	Note3
NTSC		-	$\theta = 0^\circ$	-	60	-	%	FIG.2	Note5
Viewing angle		θ Cr>10	$\phi=90^\circ$	-	80	-	deg	FIG.3	Note6
			$\phi=270^\circ$	-	80	-	deg	FIG.3	
			$\phi=0^\circ$	-	80	-	deg	FIG.3	
			$\phi=180^\circ$	-	80	-	deg	FIG.3	
Chromaticity	Red	R _X	$\theta = 0^\circ$ $\phi=0^\circ$ Ta=25°	TBD	TBD	TBD	TBD	FIG.2 CIE1931	Note5
		R _Y		TBD	TBD	TBD	TBD		
	Green	G _X		TBD	TBD	TBD	TBD		
		G _Y		TBD	TBD	TBD	TBD		
	Blue	B _X		TBD	TBD	TBD	TBD		
		B _Y		TBD	TBD	TBD	TBD		
	White	W _X		TBD	TBD	TBD	TBD		
		W _Y		TBD	TBD	TBD	TBD		

Note1. Definition of contrast ratio

Contrast ratio(Cr) is defined mathematically by the following formula. For more information see FIG.2.

$$\text{Contrast ratio} = \frac{\text{Luminance measured when LCD on the "White" state}}{\text{Luminance measured when LCD on the "Black" state}}$$

For contrast ratio, Surface Luminance, Luminance uniformity and CIE,the testing data is base on TOPCON' s BM-5 or BM-7 photo detector or compatible.

Note2. Definition of surface luminance.

Surface luminance is the luminance with all pixels displaying white. For more information see FIG.2.

L_v = Average Surface Luminance with all white pixels($P_1, P_2, P_3, \dots, P_n$)

Note3. Definition of luminance uniformity

The luminance uniformity in surface luminance is determined by measuring luminance at each test position 1 through n, and then dividing the maximum luminance of n points luminance by minimum luminance of n points luminance. For more information see FIG.2.

$$YU = \frac{\text{Minimum surface luminance with all white pixels (P1,P2,P3,\dots,Pn)}}{\text{Maximum surface luminance with all white pixels (P1,P2,P3,\dots,Pn)}}$$

Note4. Definition of response time

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time (T_r) is the time between photo detector output intensity changed from 90% to 10%. And fall time (T_f) is the time between photo detector output intensity changed from 10% to 90%.

For additional information see FIG1.

Note5. Definition of color chromaticity (CIE1931)

CIE (x,y) chromaticity, The x,y value is determined by screen active area center position P5. For more information see FIG.2.

Note6. Definition of viewing angle

Viewing angle is the angle at which the contrast ratio is greater than 10. Angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the LCD surface. For more information see FIG.3.

For viewing angle and response time testing, the testing data is base on Autronic-Melchers' s ConoScope or DMS series Instruments or compatible.

FIG.1.The definition of response Time

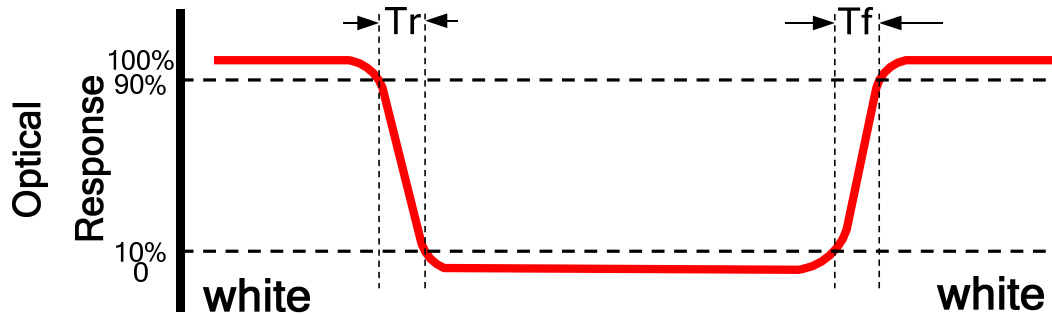


FIG.2. Measuring method for contrast ratio, surface luminance, luminance uniformity, CIE (x,y) chromaticity

Size : $S \leq 5''$ (see Figure a) A : 5 mm B : 5 mm
H,V : Active area

Light spot size $\varnothing = 5\text{mm}$ (BM-5) or $\varnothing = 7.7\text{mm}$ (BM-7) 50cm distance or compatible distance from the LCD surface to detector lens.

test spot position : see Figure a.

measurement instrument : TOPCON's luminance meter BM-5 or BM-7 or compatible (see Figure c).

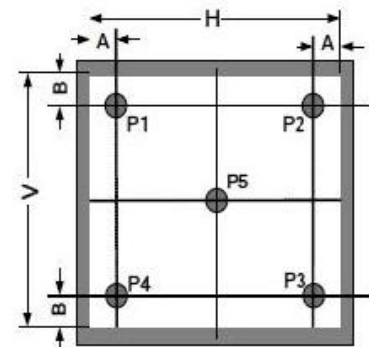


Figure a

Size : $5'' < S \leq 12.3''$ (see Figure b) H,V : Active area

Light spot size $\varnothing = 5\text{mm}$ (BM-5) or $\varnothing = 7.7\text{mm}$ (BM-7) 50cm distance or compatible distance from the LCD surface to detector lens.

test spot position : see Figure b.

measurement instrument : TOPCON's luminance meter BM-5 or BM-7 or compatible (see Figure c).

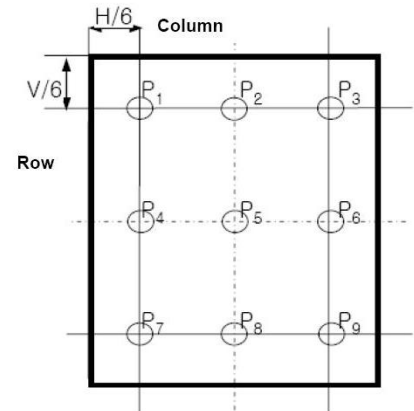


Figure b

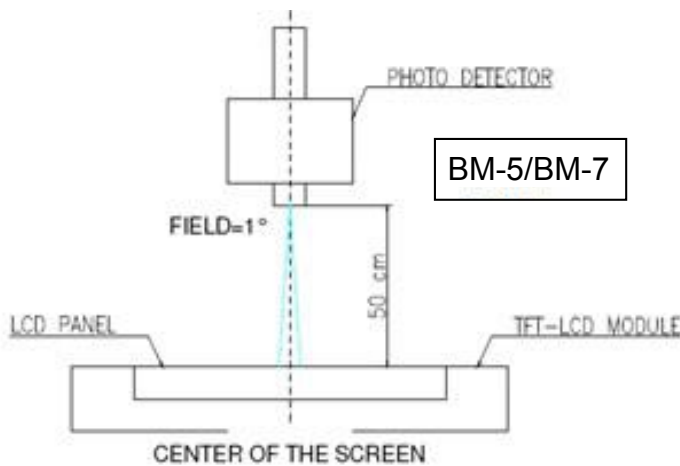
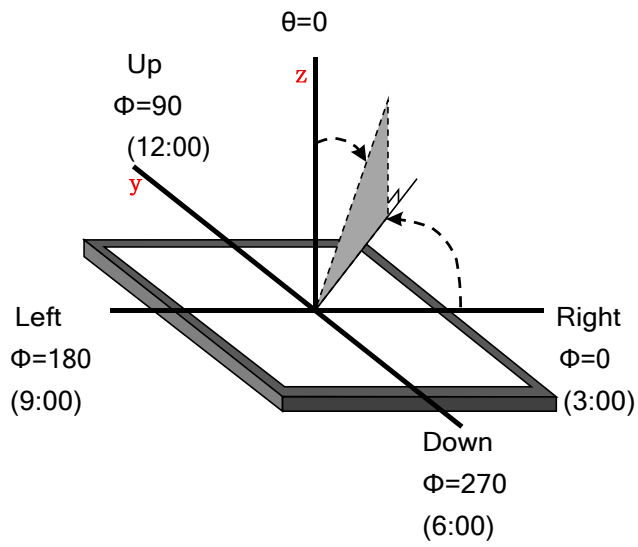


Figure c

FIG.3.The definition of viewing angle



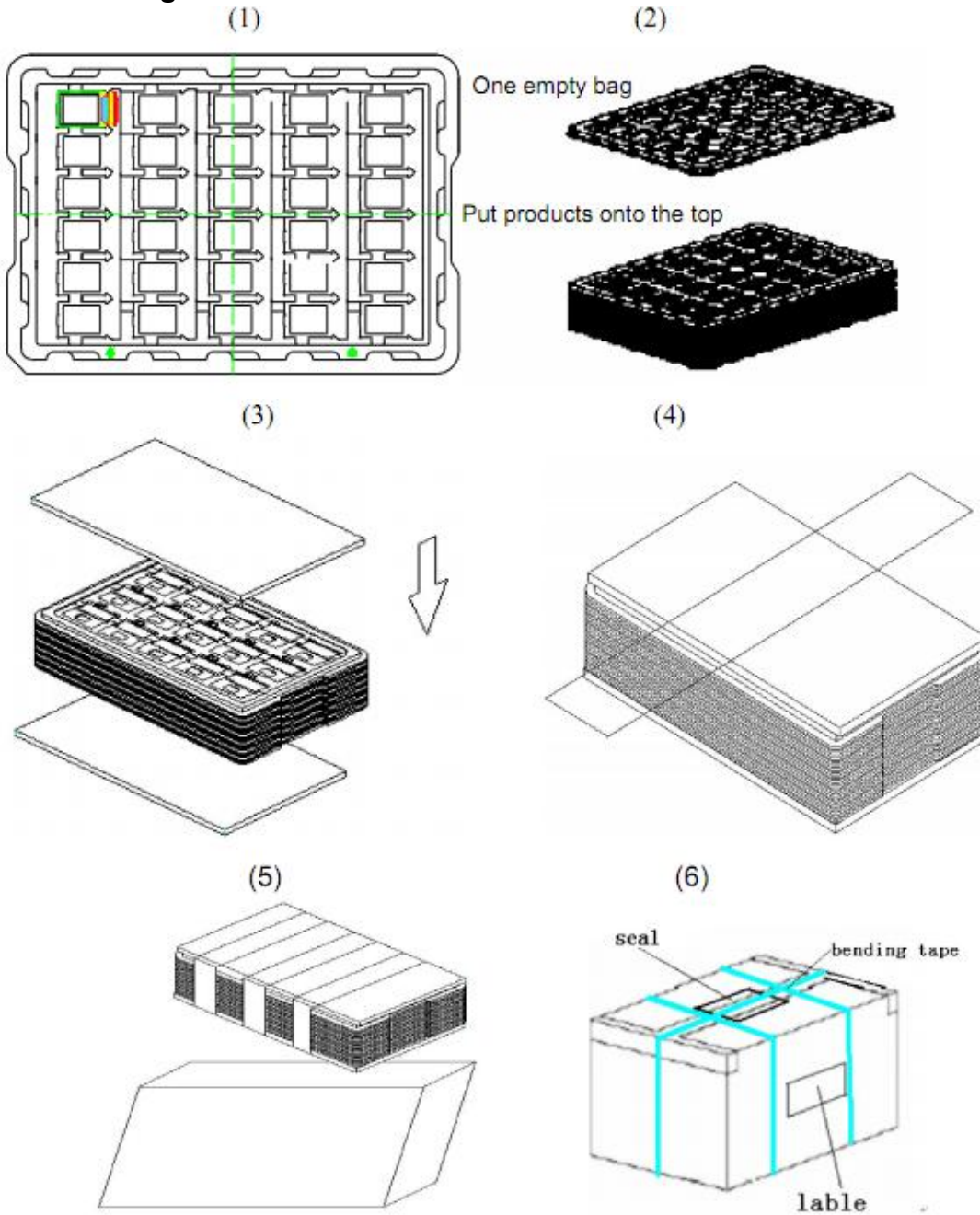
8. Environmental / Reliability Tests

No	Test Item	Condition	Remarks
1	High Temperature Operation	Ts= +70°C, 96hrs	Note 1 IEC60068-2-2, GB2423. 2-89
2	Low Temperature Operation	Ta= -20°C, 96hrs	Note 2 IEC60068-2-1 GB2423.1-89
3	High Temperature Storage	Ta= +80°C, 96hrs	IEC60068-2-2 GB2423. 2-89
4	Low Temperature Storage	Ta= -30°C, 96hrs	IEC60068-2-1 GB/T2423.1-89
5	High Temperature & Humidity Storage	Ta= +60°C, 90% RH max,96 hours	IEC60068-2-3 GB/T2423.3-2006
6	Thermal Shock (Non-operation)	-20°C 30 min ~ +60°C 30 min Change time: 5min, 30 Cycle	Start with cold temperature, end with high temperature IEC60068-2-14, GB2423.22-87
7	Electro Discharge (Operation) Static	C=150pF, R=330 Ω, 5 points/panel Air:±8KV, 5 times; Contact: ±4KV, 5 times; (Environment: 15°C ~ 35°C, 30% ~ 60%, 86Kpa ~ 106Kpa)	IEC61000-4-2 GB/T17626.2-1998
8	Vibration (Non-operation)	Frequency range: 10~55Hz, Stroke: 1.mm Sweep: 10Hz~55Hz~10Hz 2 hours for each direction of X .Y. Z. (package condition)	IEC60068-2-6 GB/T2423.5-1995
9	Shock (Non-operation)	60G 6ms, ± X, ±Y , ± Z 3 times for each direction	IEC60068-2-27 GB/T2423.5-1995
10	Package Drop Test	Height: 80 cm, 1 corner, 3 edges, 6 surfaces	IEC60068-2-32 GB/T2423.8-1995

- Note:1. Ts is the temperature of panel's surface.
2. Ta is the ambient temperature of sample.
3. The size of sample is 5pcs.

10. Packing

Packing Method



1. Put module into tray cavity:
2. Tray stacking
3. Put 1 cardboard under the tray stack and 1 cardboard above:
4. Fix the cardboard to the tray stack with adhesive tape:
5. Put the tray stack into carton.
6. Carton sealing with adhesive tape.

11. TFT-LCD Module Inspection Criteria

11.1 Scope

The incoming inspection standards shall be applied to TFT - LCD Modules (hereinafter Called "Modules") that supplied by CDTech Technology LTD.

11.2 Incoming Inspection

The customer shall inspect the modules within twenty calendar days of the delivery date (the “inspection period”) at its own cost. The result of the inspection (acceptance or rejection) shall be recorded in writing, and a copy of this writing will be promptly sent to The seller, If the results of the inspecting from buyer does not send to the seller within twenty Calendar days of the delivery date. The modules shall be regards as acceptance. Should the customer fail to notify the seller within the inspection period, the buyers Right to reject the modules shall be lapsed and the modules shall be deemed to have Been accepted by the buyer

11.3 Inspection Sampling

- 3.1. Lot size: Quantity per shipment lot per model
- 3.2. Sampling type: Normal inspection, Single sampling
- 3.3. Inspection level: II
- 3.4. Sampling table: MIL-STD-105E
- 3.5. Acceptable quality level (AQL)
Major defect: AQL=0.65 Minor defect: AQL=1.00

11.4 Inspection Conditions

4.1 Ambient conditions:

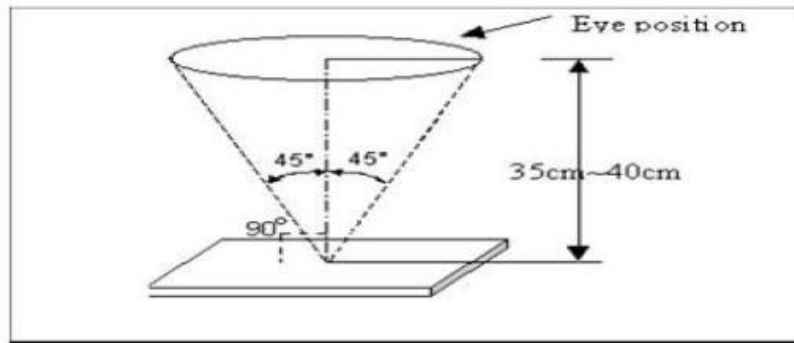
- a. Temperature: Room temperature $25 \pm 5^{\circ}\text{C}$
- b. Humidity: $(60 \pm 10) \% \text{RH}$
- c. Illumination: Single fluorescent lamp non-directive (300 to 700 Lux)

4.2 Viewing distance

The distance between the LCD and the inspector's eyes shall be at least 35 ± 5 cm.

4.3 Viewing Angle

U/D: $45^{\circ} / 45^{\circ}$, L/R: $45^{\circ} / 45^{\circ}$



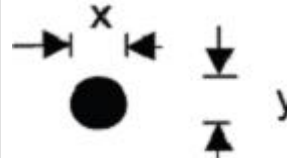
11.5 Inspection Criteria

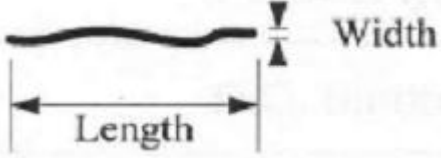

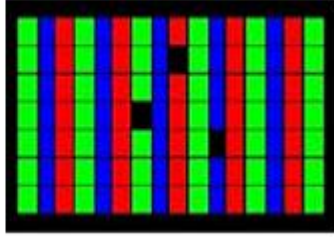
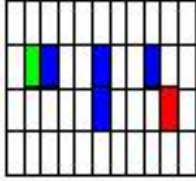
Defects are classified as major defects and minor defects according to the degree of Defectiveness defined herein.

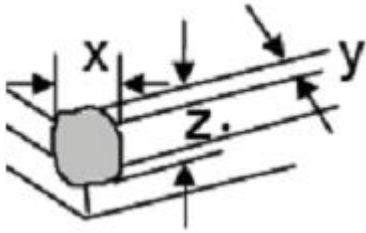
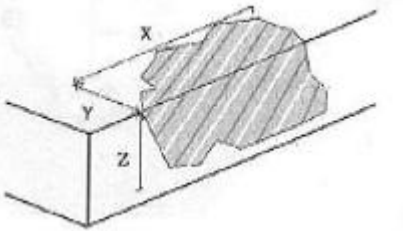
11.5.1 Major defect

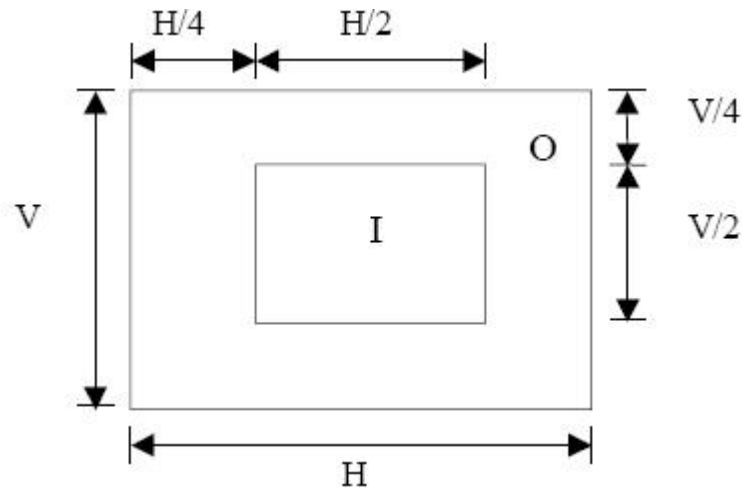
Item No	Items to be inspected	Inspection Standard
5.1.1	All functional defects	1) No display 2) Display abnormally 3) Short circuit 4) line defect
5.1.2	Missing	Missing function component
5.1.3	Crack	Glass Crack

11.5.2 Minor defect

Item No	Items to be inspected	Inspection standard	
5.2.1	Spot Defect Including Black spot White spot Pinhole Foreign particle Polarizer dirt	For dark/white spot is defined $\phi = (x+y) / 2$ 	
		Size ϕ (mm)	Acceptable Quantity
		$\phi \leq 0.05$	Ignore
		$0.05 < \phi \leq 0.15$	2
		$0.15 < \phi$	Not allowed
5.2.2	Polarizer dirt,	Size ϕ (mm)	Acceptable Quantity

	particle	$\phi \leq 0.15$	1		
		$\phi > 0.15$	Not allowed		
5.2.3	Line Defect Including Black line White line Scratch	Define: 			
		Width(mm) Length(mm)	Acceptable Quantity		
		$W \leq 0.05$	Ignore		
		$0.05 < W \leq 0.1$ $L \leq 1.5$	1		
		$0.1 < W$, or $L > 1.5$	Not allowed		
5.2.4	Polarizer Dent/Bubble	Not allowed			
5.2.5	Electrical Dot Defect	Bright and Black dot define:  and 			
		 Two Adjacent Dot			
		Inspection pattern: Full white、 Full black、 Red、 green and blue screens			
		Item	Acceptable Quantity		Note
			I	O	
Black dot defect	1		(5mm \leq Distance)		
Bright dot defect	1				
Two Adjacent Dot	Not allow				

5.2.6	Glass defect	 <p>1. Corner Fragment:</p>	
		Size(mm)	Acceptable Quantity
		$X \leq 2\text{mm}$ $Y \leq 1\text{mm}$ $Z \leq T$	Ignore T: Glass thickness X: Length Y: Width Z: thickness
		<p>2. Side Fragment:</p> 	
		Size(mm)	Acceptable Quantity
		$X \leq 5.0\text{mm}$ $Y \leq 1\text{mm}$ $Z \leq T$	T: Glass thickness X: Length Y: Width Z: thickness



I area & O area

- Note:
- 1). Dot defect is defined as the defective area of the dot area is larger than 50% of the dot area.
 - 2). The distance between two bright dot defects (red, green, blue, and white) should be larger than 15mm.
 - 3). The distance between black dot defects or black and bright dot defects should be more than 5mm apart.
 - 4). Polarizer bubble is defined as the bubble appears on active display area. The defect of polarizer bubble shall be ignored if the polarizer bubble appears on the outside of active display area.

11.6 Mechanics specification

As for the outside dimension, weight of the modules, please refer to product specification
For more details

12. Precautions for Use of LCD modules

12.1 Handling Precautions

12.1.1. The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.

12.1.2. If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.

12.1.3. Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.

12.1.4. The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.

12.1.5. If the display surface is contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:

- Isopropyl alcohol
- Ethyl alcohol

Solvents other than those mentioned above may damage the polarizer. Especially, do not use the following:

- Water
- Ketene
- Aromatic solvents

12.1.6. Do not attempt to disassemble the LCD Module.

12.1.7. If the logic circuit power is off, do not apply the input signals.

12.1.8. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.

12.1.8.1. Be sure to ground the body when handling the LCD Modules.

12.1.8.2. Tools required for assembly, such as soldering irons, must be properly ground.

12.1.8.3. To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.

12.1.8.4. The LCD Module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

12.2 Storage Precautions

12.2.1. When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps.

12.2.2. The LCD modules should be stored under the storage temperature range. If the LCD modules will be stored for a long time, the recommend condition is:

Temperature : 0°C ~ 40°C Relatively humidity: ≤80%

12.2.3. The LCD modules should be stored in the room without acid, alkali and harmful gas.



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12.3 Transportation Precautions

The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.